

## HIGH SPEED 3.3 VOLT 2K x 8 CMOS PROM/RPROM

### KEY FEATURES

- 3.3 Volt  $\pm$  0.3 Volt  $V_{CC}$
- Fast Access Time
  - $t_{ACC} = 70$  ns
  - $t_{CS} = 20$  ns
- Low Power Consumption
  - $\leq 25$  mA  $I_{CC}$
- Available in 300 Mil "Skinny" DIP
- Immune to Latch-up
  - Up to 200 mA
- ESD Protection Exceeds 2000V

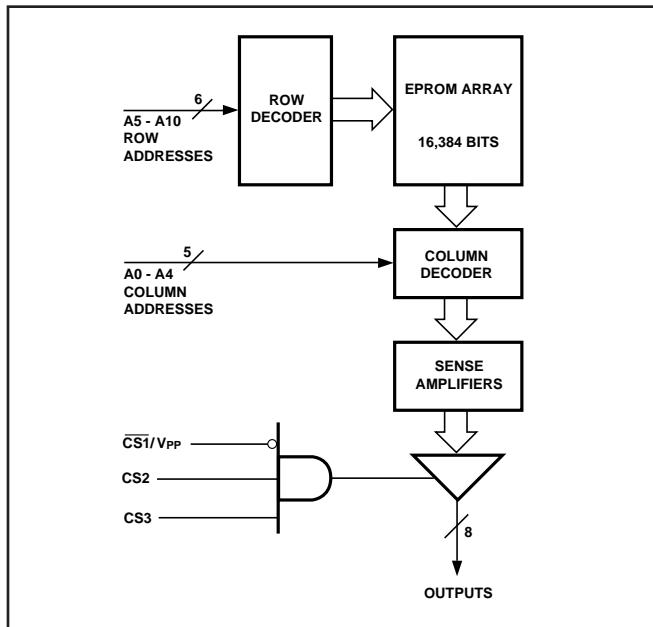
### GENERAL DESCRIPTION

The WS57LV291C is a High Performance 2K x 8 UV Erasable Read Only Memory (RPROM). This RPROM is manufactured using an advanced CMOS EPROM manufacturing process resulting in a very low power die that affords exceptional speed capabilities with a 3.3 volt  $V_{CC}$  supply. The WS57LV291C is configured in the standard Bipolar PROM pinouts, the preferred and most common pinout for high speed PROMs of 16K density.

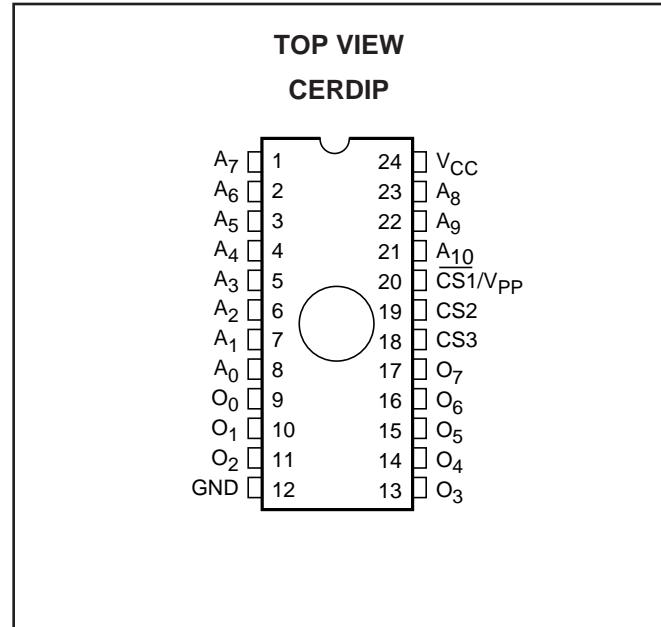
Operating at 3.3 volts, the WS57LV291C dissipates a maximum of 25 mA under worst case conditions at maximum speed (70 ns  $T_{AA}$ ). Typical  $I_{CC}$  at 25°C is less than 20 millamps.

The WS57LV291C is packaged in a space saving 300 mil windowed, hermetic DIP package.

### BLOCK DIAGRAM



### PIN CONFIGURATION



### PRODUCT SELECTION GUIDE

| PARAMETER                     | WS57LV291C-70 | WS57LV291C-90 |
|-------------------------------|---------------|---------------|
| Address Access Time (Max)     | 70 ns         | 90 ns         |
| CS to Output Valid Time (Max) | 20 ns         | 30 ns         |

**ABSOLUTE MAXIMUM RATINGS\***

Storage Temperature..... $-65^{\circ}$  to  $+150^{\circ}$ C  
 Voltage on any Pin with Respect to Ground..... $-0.6V$  to  $+7V$   
 V<sub>PP</sub> with Respect to Ground..... $-0.6V$  to  $+14V$   
 ESD Protection.....>2000V

**\*NOTICE:**

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect device reliability.

**MODE SELECTION**

| PINS<br>MODE \ | CS1/<br>V <sub>PP</sub> | CS2             | CS3             | V <sub>CC</sub> | OUTPUTS          |
|----------------|-------------------------|-----------------|-----------------|-----------------|------------------|
| Read           | V <sub>IL</sub>         | V <sub>IH</sub> | V <sub>IH</sub> | V <sub>CC</sub> | D <sub>OUT</sub> |
| Output Disable | V <sub>IH</sub>         | X               | X               | V <sub>CC</sub> | High Z           |
| Output Disable | X                       | V <sub>IL</sub> | X               | V <sub>CC</sub> | High Z           |
| Output Disable | X                       | X               | V <sub>IL</sub> | V <sub>CC</sub> | High Z           |
| Program        | V <sub>PP</sub>         | X               | X               | V <sub>CC</sub> | D <sub>IN</sub>  |
| Program Verify | V <sub>IL</sub>         | V <sub>IH</sub> | V <sub>IH</sub> | V <sub>CC</sub> | D <sub>OUT</sub> |

**OPERATING RANGE**

| RANGE      | TEMPERATURE  | V <sub>CC</sub>   |
|------------|--------------|-------------------|
| Commercial | 0°C to +70°C | + 3.3V $\pm$ 0.3V |

**DC READ CHARACTERISTICS** Over Operating Range. (See Above)

| SYMBOL          | PARAMETER                             | TEST CONDITIONS   | MIN  | MAX                   | UNITS   |
|-----------------|---------------------------------------|---|------|-----------------------|---------|
|                 |                                       |   |      |                       |         |
| V <sub>IL</sub> | Input Low Voltage                     | (Note 3)  | -0.1 | 0.6                   | V       |
| V <sub>IH</sub> | Input High Voltage                    | (Note 3)  | 2.0  | V <sub>CC</sub> + 0.3 | V       |
| V <sub>OL</sub> | Output Low Voltage                    | I <sub>OL</sub> = 16 mA   |      | 0.4                   | V       |
| V <sub>OH</sub> | Output High Voltage                   | I <sub>OH</sub> = -4 mA   | 2.4  |                       | V       |
| I <sub>CC</sub> | V <sub>CC</sub> Active Current (CMOS) | (Notes 1 and 2)<br>I <sub>CC</sub> at Maximum Frequency<br>Outputs Not Loaded |      | 25                    | mA      |
| I <sub>LI</sub> | Input Leakage Current                 | V <sub>IN</sub> = 3.6V or Gnd   | -10  | 10                    | $\mu$ A |
| I <sub>LO</sub> | Output Leakage Current                | V <sub>OUT</sub> = 3.6 V or Gnd   | -10  | 10                    | $\mu$ A |

NOTES: 1. CMOS inputs: GND  $\pm$  0.3V or V<sub>CC</sub>  $\pm$  0.3V.

2. For TTL inputs add 5 mA I<sub>CC</sub>.

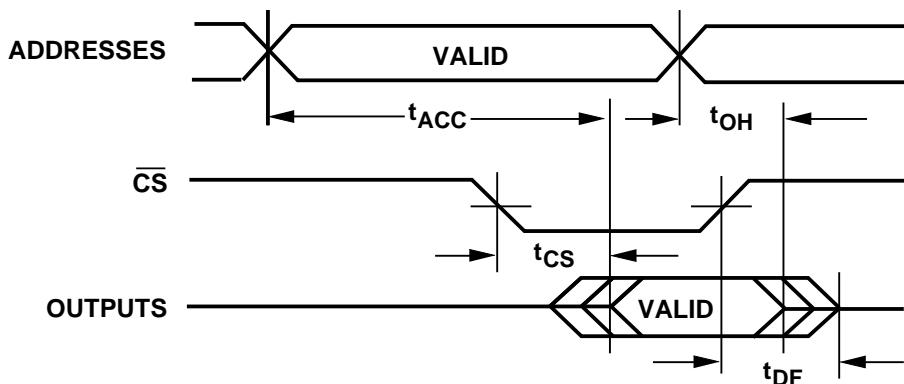
3. These are absolute voltages with respect to device ground pin and include all overshoots due to system and/or tester noise.  
Do not attempt to test these values without suitable equipment.

**AC READ CHARACTERISTICS** Over Operating Range. (See Above)

| PARAMETER                       | SYMBOL           | WS57LV291C-70 |     | WS57LV291C-90 |     | UNITS |
|---------------------------------|------------------|---------------|-----|---------------|-----|-------|
|                                 |                  | MIN           | MAX | MIN           | MAX |       |
| Address to Output Delay         | t <sub>ACC</sub> |               | 70  |               | 90  |       |
| CS to Output Delay              | t <sub>CS</sub>  |               | 20  |               | 30  |       |
| Output Disable to Output Float* | t <sub>DF</sub>  |               | 20  |               | 30  |       |
| Address to Output Hold          | t <sub>OH</sub>  | 0             |     | 0             |     | ns    |

\*Sampled, Not 100% Tested.

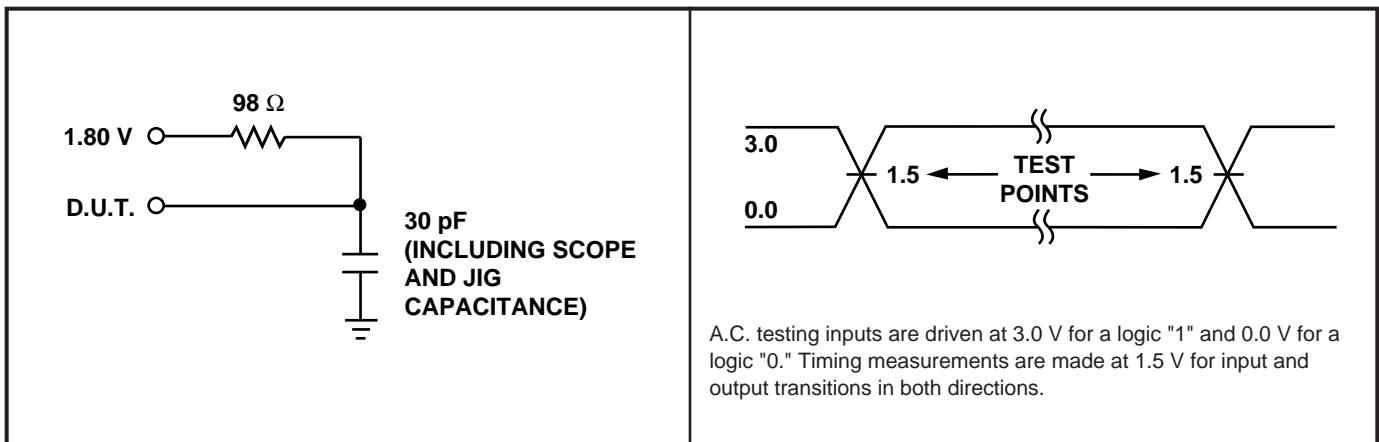


**AC READ TIMING DIAGRAM**

**CAPACITANCE<sup>(4)</sup>**  $T_A = 25^\circ\text{C}$ ,  $f = 1 \text{ MHz}$

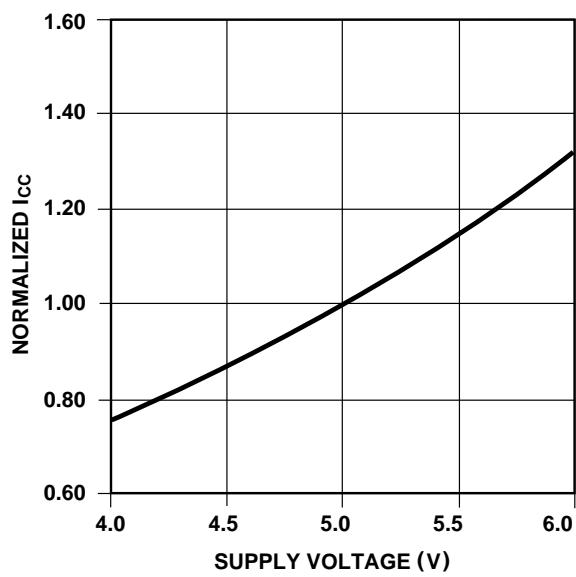
| SYMBOL    | PARAMETER            | CONDITIONS             | TYP <sup>(5)</sup> | MAX | UNITS |
|-----------|----------------------|------------------------|--------------------|-----|-------|
| $C_{IN}$  | Input Capacitance    | $V_{IN} = 0\text{V}$   | 4                  | 6   | pF    |
| $C_{OUT}$ | Output Capacitance   | $V_{OUT} = 0\text{V}$  | 8                  | 12  | pF    |
| $C_{VPP}$ | $V_{PP}$ Capacitance | $V_{PP} = 0 \text{ V}$ | 18                 | 25  | pF    |

**NOTES:** 4. This parameter is only sampled and is not 100% tested.  
5. Typical values are for  $T_A = 25^\circ\text{C}$  and nominal supply voltages.

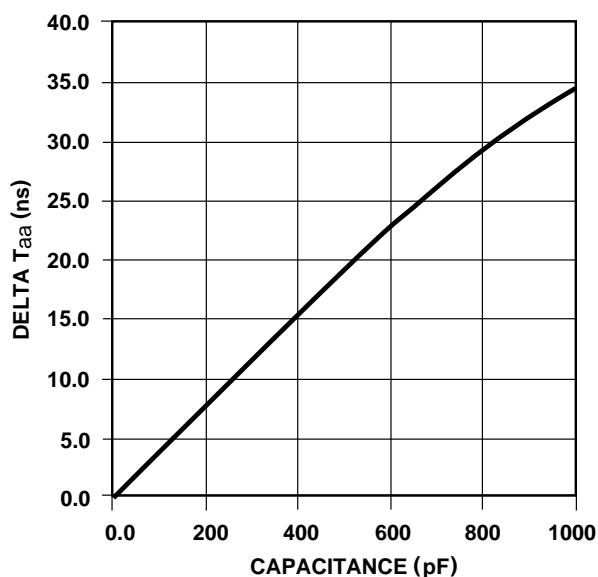
**TEST LOAD** (High Impedance Test Systems)**A.C. TESTING INPUT/OUTPUT WAVEFORM**

**NOTE:** 6. Provide adequate decoupling capacitance as close as possible to this device to achieve the published A.C. and D.C. parameters. A 0.1 microfarad capacitor in parallel with a 0.01 microfarad capacitor connected between  $V_{CC}$  and ground is recommended. Inadequate decoupling may result in access time degradation or other transient performance failures.

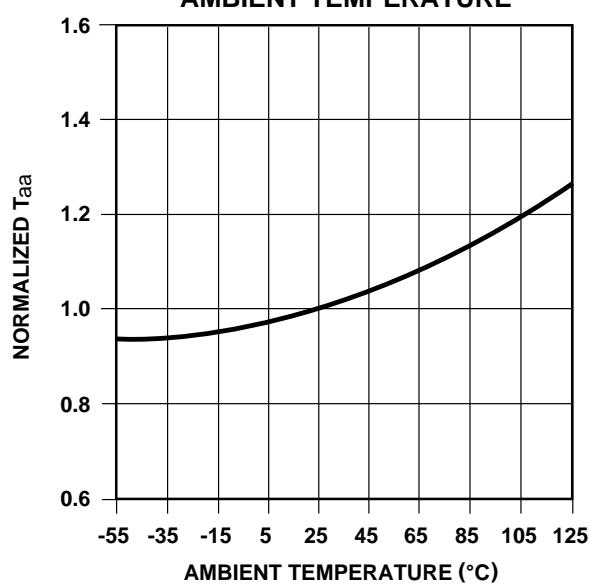
**NORMALIZED SUPPLY CURRENT  
vs.  
SUPPLY VOLTAGE**



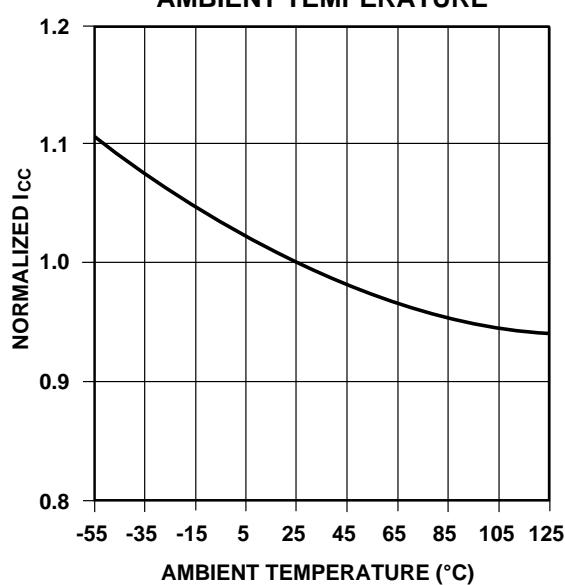
**TYPICAL ACCESS TIME CHANGE  
vs.  
OUTPUT LOADING**



**NORMALIZED  $T_{aa}$   
vs.  
AMBIENT TEMPERATURE**



**NORMALIZED SUPPLY CURRENT  
vs.  
AMBIENT TEMPERATURE**

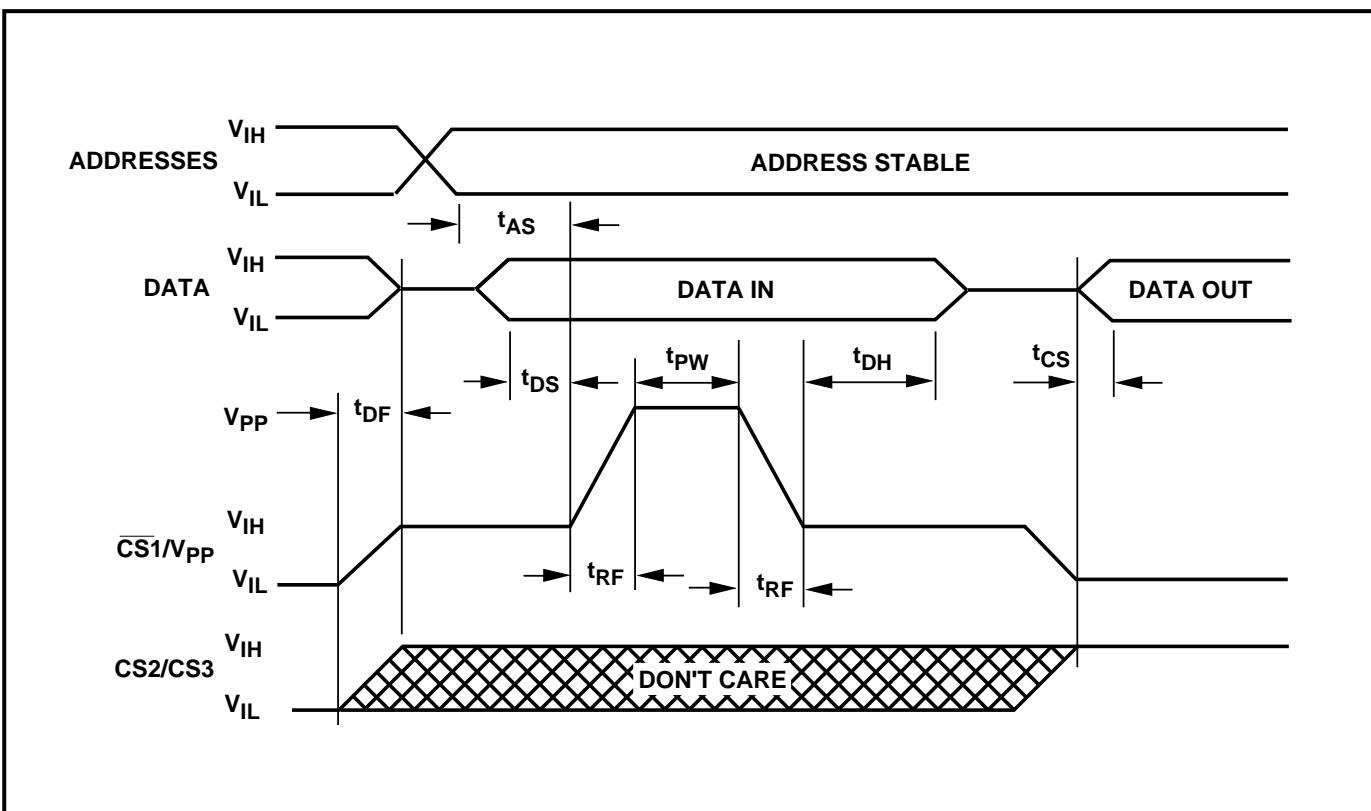


**PROGRAMMING INFORMATION****DC CHARACTERISTICS** ( $T_A = 25 \pm 5^\circ\text{C}$ ,  $V_{CC} = 6.25 \text{ V} \pm 0.25 \text{ V}$ ,  $V_{PP} = 12.75 \pm 0.25 \text{ V}$ )

| SYMBOLS  | PARAMETER   | MIN | MAX  | UNITS         |
|----------|---|-----|------|---------------|
| $I_{LI}$ | Input Leakage Current<br>( $V_{IN} = V_{CC}$ or Gnd)              | -10 | 10   | $\mu\text{A}$ |
| $I_{PP}$ | $V_{PP}$ Supply Current During Programming Pulse                  |     | 60   | mA            |
| $I_{CC}$ | $V_{CC}$ Supply Current   |     | 25   | mA            |
| $V_{OL}$ | Output Low Voltage During Verify<br>( $I_{OL} = 16 \text{ mA}$ )  |     | 0.45 | V             |
| $V_{OH}$ | Output High Voltage During Verify<br>( $I_{OH} = -4 \text{ mA}$ ) | 2.4 |      | V             |

NOTES: 7.  $V_{PP}$  must not be greater than 13 volts including overshoot.**AC CHARACTERISTICS** ( $T_A = 25 \pm 5^\circ\text{C}$ ,  $V_{CC} = 6.25 \text{ V} \pm 0.25 \text{ V}$ ,  $V_{PP} = 12.75 \pm 0.25 \text{ V}$ )

| SYMBOLS  | PARAMETER                   | MIN | TYP | MAX | UNITS         |
|----------|-----------------------------|-----|-----|-----|---------------|
| $t_{AS}$ | Address Setup Time          | 2   |     |     | $\mu\text{s}$ |
| $t_{DF}$ | Chip Disable Setup Time     |     |     | 30  | ns            |
| $t_{DS}$ | Data Setup Time             | 2   |     |     | $\mu\text{s}$ |
| $t_{PW}$ | Program Pulse Width         | 100 |     | 200 | $\mu\text{s}$ |
| $t_{DH}$ | Data Hold Time              | 2   |     |     | $\mu\text{s}$ |
| $t_{CS}$ | Chip Select Delay           |     |     | 30  | ns            |
| $t_{RF}$ | $V_{PP}$ Rise and Fall Time | 1   |     |     | $\mu\text{s}$ |

**PROGRAMMING WAVEFORM**

**ORDERING INFORMATION**

| PART NUMBER    | SPEED (ns) | PACKAGE TYPE        | PACKAGE DRAWING | OPERATING TEMPERATURE RANGE | WSI MANUFACTURING PROCEDURE |
|----------------|------------|---------------------|-----------------|-----------------------------|-----------------------------|
| WS57LV291C-70T | 70         | 24 Pin CERDIP, 0.3" | T1              | Comm'l                      | Standard                    |
| WS57LV291C-90T | 90         | 24 Pin CERDIP, 0.3" | T1              | Comm'l                      | Standard                    |

**NOTE:** 8. The actual part marking will not include the initials "WS."

**PROGRAMMING/ALGORITHMS/ERASURE/PROGRAMMERS**

**REFER TO  
PAGE 5-1**

The WS57LV291C is programmed using Algorithm D shown on page 5-9.

